

Title (en)

Method for manufacturing conductive wood material boards and same

Title (de)

Verfahren zur Herstellung von leitfähigen Holzwerkstoffplatten und solche Holzwerkstoffplatten

Title (fr)

Procédé de fabrication de plaques en bois conductrices et de telles plaques en bois conductrices

Publication

EP 2027979 B1 20130306 (DE)

Application

EP 08014789 A 20080820

Priority

DE 102007039267 A 20070820

Abstract (en)

[origin: EP2027979A1] The method involves providing a preform with a main portion of lignocellulose containing fibers, chips and strands mixed with an adhesive, and hot pressing a conductive wood material board i.e. medium density fiberboard. The hot-pressed wood material board is powder-coated. The adhesive is made of a phenol-formaldehyde adhesive and a low molecular protein-containing component e.g. wheat protein-containing component, for increasing the conductivity of the wood material board. An alkali, earth alkali or ammonium salt is utilized.

IPC 8 full level

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CPC (source: EP)

B27N 3/00 (2013.01); **B27N 3/002** (2013.01); **B27N 7/005** (2013.01)

Cited by

CN105235048A; CN103072179A; EP3017924A1; RU2667757C1; EP3181315A1; DE102008049132A1; US10369721B2; US11072087B2

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